

Title (en)

POST-TREATMENT METHOD AND DEVICE THEREFOR

Title (de)

NACHBEHANDLUNGSVERFAHREN SOWIE VORRICHTUNG HIERFÜR

Title (fr)

PROCEDE DE POST-TRAITEMENT ET DISPOSITIF APPROPRIE

Publication

**EP 1960180 A1 20080827 (DE)**

Application

**EP 06830152 A 20061128**

Priority

- EP 2006069002 W 20061128
- DE 102005057465 A 20051130

Abstract (en)

[origin: DE102005057465A1] In a method for post-treatment of an injection molding, in which the molding (5) is delivered from the injection mold into a receiving element (1), the molding is at least temporarily held out of contact with the receiving element. An independent claim is included for a system for post-treatment of an injection molding, which includes a device for holding the molding in a contact-free manner.

IPC 8 full level

**B29C 49/64** (2006.01); **B29C 35/16** (2006.01); **B29C 45/72** (2006.01)

CPC (source: EP US)

**B29C 35/16** (2013.01 - EP); **B29C 45/7207** (2013.01 - EP); **B29C 49/12** (2013.01 - US); **B29C 49/42065** (2022.05 - US); **B29C 35/045** (2013.01 - EP); **B29C 49/06** (2013.01 - EP); **B29C 49/12** (2013.01 - EP); **B29C 49/4205** (2013.01 - EP); **B29C 49/42105** (2022.05 - EP); **B29C 49/42421** (2022.05 - EP); **B29C 49/42428** (2022.05 - EP); **B29C 49/6427** (2013.01 - EP); **B29C 49/6436** (2013.01 - EP); **B29C 49/645** (2022.05 - EP); **B29C 49/681** (2022.05 - EP); **B29C 2035/1658** (2013.01 - EP); **B29C 2045/7214** (2013.01 - EP); **B29C 2049/023** (2013.01 - EP); **B29C 2949/0715** (2022.05 - EP); **B29C 2949/072** (2022.05 - EP); **B29C 2949/0744** (2022.05 - EP); **B29C 2949/3008** (2022.05 - EP); **B29C 2949/3012** (2022.05 - EP); **B29C 2949/3016** (2022.05 - EP); **B29C 2949/302** (2022.05 - EP); **B29C 2949/3026** (2022.05 - EP); **B29C 2949/3032** (2022.05 - EP); **B29C 2949/3064** (2022.05 - EP); **B29C 2949/308** (2022.05 - EP); **B29K 2067/00** (2013.01 - EP); **B29K 2105/253** (2013.01 - EP); **B29L 2031/7158** (2013.01 - EP)

Designated contracting state (EPC)

AT CH DE LI LU

DOCDB simple family (publication)

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